

ABSTRACT OF THE DISCLOSURE

A camera module including a light-transmissible board 10 having infrared rays cutting function on one surface of which a wiring pattern 13 is formed, an image pickup element 11 having a photodetecting portion 15 which is flip-chip-mounted on the same surface of the light-transmissible board 10 while the photodetecting portion 15 is opposite to an area where there is no wiring-pattern 13, and a lens unit 12 which is mounted on the other surface of the light-transmissible board 10 so as to be located above the photodetecting portion 15 of the image pickup element 11.